

Application. No. : 10/022,297
Filing Date : December 12, 2001
Amendment Date : May 24, 2004
Office Action Date : March 30, 2004

AMENDMENTS TO THE CLAIMS

The following listing of claims replaces all prior versions of the claims and any prior listing of the claims in the present application. The listing of claims presents each claim with its respective status shown in parentheses. All original claims and previously presented claims appear as clean text.

Claims 1-3, 5-12, 17-18, 23-24, and 27-32 were previously canceled.

Claims 16, 19-22, 25-26, and 33-37 are canceled herein.

Claims 4 and 13-15 remain as originally filed or as previously amended.

Listing of Claims

Claims 1-3 (Canceled)

Claim 4 (Previously Presented) A semiconductor device comprising an aluminum substrate, a copper land formed on the substrate, a semiconductor chip mounted on the land, a solder layer only through which the semiconductor chip is joined with the land, and an epoxide synthetic resin, the epoxide synthetic resin having a coefficient of expansion generally less than approximately 23 ppm/°K and generally greater than the coefficient of expansion of the copper land, the epoxide synthetic resin covering the land, the solder layer, and the semiconductor chip.

Claim 5-12 (Canceled)

Claim 13 (Previously Presented) The semiconductor device as set forth in Claim 4, wherein the semiconductor chip defines at least two corners positioned generally opposite to each other, the land has an outer boundary that defines at least two corner portions in proximity to the corners of the semiconductor chip, the outer boundary further defines contiguous portions extending next to the corner portions and spaced apart from the semiconductor chip more than the corner portions, and the corner portions of the land generally confine the corners of the semiconductor chip therein.

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Claim 14 (Previously Presented) The semiconductor device as set forth in Claim 4, wherein the semiconductor chip controls electric power.

Claim 15 (Original) The semiconductor device as set forth in Claim 14, wherein the semiconductor chip controls power of an electric motor arranged to drive an electric vehicle.

Claim 16-37 (Canceled)